L Number	Hits	Search Text	DB	Time stamp
1	184	(semiconductor or die or chip or IC) same	USPAT	2004/09/23 23:06
-	201	heat near shield	0011	2001,03,23 23.00
2	97	(semiconductor or die or chip or IC) with heat near shield	USPAT	2004/09/23 23:09
3	92	(semiconductor or die or chip or IC) with	USPAT	2004/09/23 23:15
_	1	heat adj shield "20040061213"	USPAT;	2004/09/22 16:24
-	3510	257/678	US-PGPUB USPAT;	2004/09/21 19:41
_	1194	257/685	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/21 19:57
-	2773	257/686	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/09/21 20:37
-	2458	257/706	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/09/21 21:08
-	1157	257/720	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/09/22 10:50
 -	3775	257/723	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/09/22 11:09
_	2547	257/777	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/09/22 11:32
-	4116	257/778	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/09/22 12:15
_	2643	257/784	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/09/22 13:47
_	5	5550711.pn. 5898219.pn. 6201302.pn. 6489676.pn.	DERWENT; IBM_TDB USPAT	2004/09/22 13:38
_	2	6538319.pn. 6737750.pn.	USPAT	2004/09/22 13:44

-	12	6274930.pn.	USPAT;	2004/09/22 13:44
		6340846.pn.	US-PGPUB	
		6376904.pn.		
1		6388313.pn.		
		6400007.pn.		
		6414381.pn.		
}		6424050.pn.		
1		20020004258.pn.	•	
		20020014689.pn.		
]		20020125557.pn.		
1		20020125558.pn.		
		20020130404.pn.		
	4700		ricoam.	2004/09/22 14:06
-	4700	257/787	USPAT;	2004/03/22 14.00
			US-PGPUB;	1
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	·
-	951	438/122	USPĀT;	2004/09/22 14:22
			US-PGPUB;	
1			EPO; JPO;	
			DERWENT;	
	2	420 /100	IBM_TDB	1 2004/00/00 15 11
-	2154	438/108	USPAT;	2004/09/22 15:11
1			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	1018	438/109	USPAT;	2004/09/22 15:23
	1010	430/103	US-PGPUB;	2001,03,22 13.23
			· ·	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
1-	3797	361/760	USPAT;	2004/09/22 15:29
			US-PGPUB;	
			EPO; JPO;	1
			DERWENT;	
			IBM TDB	
	٥٠	#621 6020#	USPAT;	2004/09/22 16:11
-	25	"6316838"		2004/09/22 16:11
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	1
1			IBM_TDB	
-	1		USPAT	2004/09/22 15:32
l_	1		USPAT	2004/09/22 15:33
_	1		USPAT	2004/09/22 15:33
_	1		USPAT	2004/09/22 15:33
-	_		USPAT	2004/09/22 15:33
-	1		l .	2004/09/22 15:33
-	1		USPAT	
-	1		USPAT	2004/09/22 15:34
-	1		USPAT	2004/09/22 15:34
-	1		USPAT	2004/09/22 15:35
_	1		USPAT	2004/09/22 15:35
-	1		USPAT	2004/09/22 15:35
_	1		USPAT	2004/09/22 15:36
1_	1		USPAT	2004/09/22 15:36
-				2004/09/22 15:36
-	1		USPAT	
1 - 1	1		USPAT	2004/09/22 15:41
-	1		USPAT	2004/09/22 15:42
-	1		USPAT	2004/09/22 15:42
-	1		USPAT	2004/09/22 15:43
_	1		USPAT	2004/09/22 15:43
_	ĺ		USPAT	2004/09/22 15:43
_	أ أ	"electromagnetic near shield" same heat	USPAT;	2004/09/22 16:25
	l	near (spread\$3 or sink or transfer or	US-PGPUB	= 30.7, 03, 22 10.23
			US-FGFUB	
		dissipation)		0004/00/00 15 :=
-	535	((electromagnetic or electrical) near	USPAT;	2004/09/22 16:47
		shield) and heat near (spread\$3 or sink or	US-PGPUB	
		transfer or dissipation)		1
1 -	131	((electromagnetic or electrical) near	USPAT;	2004/09/22 16:27
		shield) same heat near (spread\$3 or sink	US-PGPUB	
		or transfer or dissipation)		
L		or cranorer or arosipacton/	I .	L

-	13	(((electromagnetic or electrical) near	USPAT;	2004/09/22 16:40
		shield) same heat near (spread\$3 or sink	US-PGPUB	
		or transfer or dissipation)) and ("RF" or		
		radio near frequence) near (chip or die or		
		IC or semiconductor)		1
-	0	(((electromagnetic or electrical) near	USPAT	2004/09/22 16:42
		shield) and heat near (spread\$3 or sink or		
		transfer or dissipation)) and ("RF" or		
		radio near frequence) near (chip or die or		
		IC or semiconductor)		1
l_	ا ا	(((electromagnetic or electrical) near	USPAT	2004/09/22 16:43
	ľ	shield) and heat near (spread\$3 or sink or	001711	2004,03,22 10.13
		transfer or discinstically and ("DE" or	1	
		transfer or dissipation)) and ("RF" or		-
		radio near frequency) near (chip or die or	!	
		IC or semiconductor)		0004/00/00 16 40
-	12		USPAT	2004/09/22 16:48
		shield) and heat near (spread\$3 or sink or		
		transfer or dissipation)) and ("RF" or		
	!	radio near frequency) with (chip or die or		
		IC or semiconductor)		ł
-	1884	((electromagnetic or electrical or EMI)	USPAT;	2004/09/22 17:02
		near shield\$3) and heat near (spread\$3 or	US-PGPUB	
		sink or transfer or dissipation)		
1_	52		USPAT	2004/09/22 17:01
1		near shield\$3) and heat near (spread\$3 or		
		sink or transfer or dissipation)) and		
		("RF" or radio near frequency) with (chip		
		or die or IC or semiconductor)	!	
1	ے ا		USPAT	2004/09/22 17:03
-	6	, , , ,	USPAI	2004/09/22 17:03
	}	near shield\$3) and heat near (spread\$3 or		
	1	sink or transfer or dissipation)) and		
		("RF" or radio near frequency) near (chip	Į.	
		or die or IC or semiconductor)		
-	4024	((electromagnetic or electrical or EMI)	USPAT;	2004/09/22 17:23
		with shield\$3) and heat near (spread\$3 or	US-PGPUB	
		sink or transfer or dissipation)		
_	9		USPAT	2004/09/22 17:23
		with shield\$3) and heat near (spread\$3 or		
		sink or transfer or dissipation)) and		<u>'</u>
		("RF" or radio near frequency) near (chip		
	1	or die or IC or semiconductor)		
 	105		USPAT	2004/09/22 17:22
		with shield\$3) and heat near (spread\$3 or		
		sink or transfer or dissipation)) and		
		("RF" or radio near frequency) with (chip		
	1	or die or IC or semiconductor)	1	
1_	10411	((electromagnetic or electrical or EMI)	USPAT	2004/09/22 17:23
	10311	with shield\$3) and heat		
1_	13	l	USPAT	2004/09/23 13:33
-	13	with shield\$3) and heat) and ("RF" or	332777	1 2001,03,23 13.33
1		radio near frequency) near (chip or die or		
				1
1	_	IC or semiconductor)	HCDAM	2004/09/23 13:35
-	0	embedded near ground near plane same heat	USPAT	2004/09/23 13:35
		near dissipation and ground near plane		1
		with electrical near shield\$3		0004/00/00 10 55
-	7	ground near plane same heat near	USPAT	2004/09/23 13:53
		dissipation and ground near plane with		
		electrical near shield\$3		l
-	14	ground near plane same heat and ground	USPAT	2004/09/23 14:06
		near plane with electrical near shield\$3		
-	30	ground near plane same heat and ground	USPAT	2004/09/23 14:29
		near plane same electrical near shield\$3		
-	30	ground near (plane or layer or film or	USPAT	2004/09/23 14:29
1		plate) same heat and ground near plane		
		same electrical near shield\$3		1
_	65	ground near (plane or layer or film or	USPAT	2004/09/23 14:29
1		plate) and heat and ground near plane		
		same electrical near shield\$3		
1_	32		USPAT	2004/09/23 14:37
1-	32		30171	2004,05,25 14.5/
1		plate) same heat and ground near (plane	1	l
1		an lawar an film an wlatel same alastudes!	1	1
		or layer or film or plate) same electrical near shield\$3		

-	29	1 2	USPAT	2004/09/23 14:37
		plate) and heat near dissipat\$3 and ground		
		near (plane or layer or film or plate)		
		same electrical near shield\$3		
-	63	ground near (plane or layer or film or	USPAT	2004/09/23 14:38
		plate) and heat near dissipat\$3 and ground		
		near (plane or layer or film or plate)		
		same (electrical or electro\$5 or EMI) near		
		shield\$3		
_	15	ground near (plane or layer or film or	USPAT	2004/09/23 14:43
		plate) same heat near dissipat\$3 and		
1		ground near (plane or layer or film or		
		plate) same (electrical or electro\$5 or		
		EMI) near shield\$3		
_	30		USPAT	2004/09/23 14:54
		plate) same heat near dissipat\$3 and	002	=====================================
		ground near (plane or layer or film or		
		plate) same (electrical or electro\$5 or		
		EMI) with shield\$3		
_	122	1	USPAT	2004/09/23 14:55
-	122	plate) same heat and ground near (plane or	USIAI	2004/03/23 14.55
		layer or film or plate) same (electrical		
		or electro\$5 or EMI) with shield\$3		
	70		USPAT	2004/09/23 14:55
_	, ,	plate) with heat and ground near (plane or	ODIM	2004/03/23 14:33
		layer or film or plate) same (electrical		
		or electro\$5 or EMI) with shield\$3		
	51		USPAT	2004/09/23 15:02
-	31	plate) with heat and ground near (plane or	USIAI	2004703723 13.02
		layer or film or plate) with (electrical		
		or electro\$5 or EMI) with shield\$3		
	71	(ground near (plane or layer or film or	USPAT	2004/09/23 15:09
-	/ 1	plate same heat and ground near (plane or	OSEAL	2004/03/23 13.03
		layer or film or plate) same (electrical		
		or electro\$5 or EMI) with shield\$3) not (
		ground near (plane or layer or film or		
		plate) with heat and ground near (plane or		
		layer or film or plate) with (electrical		
		or electro\$5 or EMI) with shield\$3)		
	L	or erectrosp or FMT) with surerdss)	<u> </u>	1